Chip-Bridge Technologies

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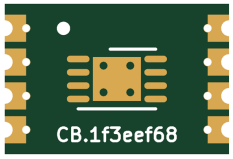


Host: 8-SOIC 5.275x5.275mm — Guest: 8-TDFN 3x2mm

Adapter Interfaces

Table 1: Adapter Parameters

Parameter	Host	Guest	Unit
Package	SOIC	TDFN	-
Pin Count	8	8	-
Package Dim.	5.275x5.275	3x2	mm
Pitch	1.27	0.5	mm

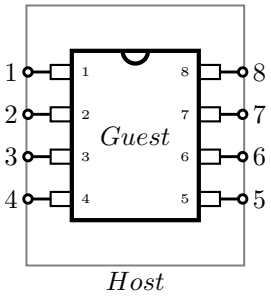


Figure 1: Adapter Pinout

Host Pins	Guest Pins
1	1
2	2
3	3
4	4
5	5
6	6
7	7
8	8

Table 2: Pin Configuration

Features

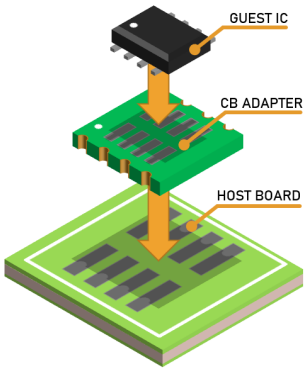
- Drop-in adapter; Install 8-TDFN 3x2mm on a 8-SOIC 5.275x5.275mm footprint
- Low profile adapter, 0.8mm
- Supports common manufacturing methods
- 1:1 Pinout Configuration

General Description

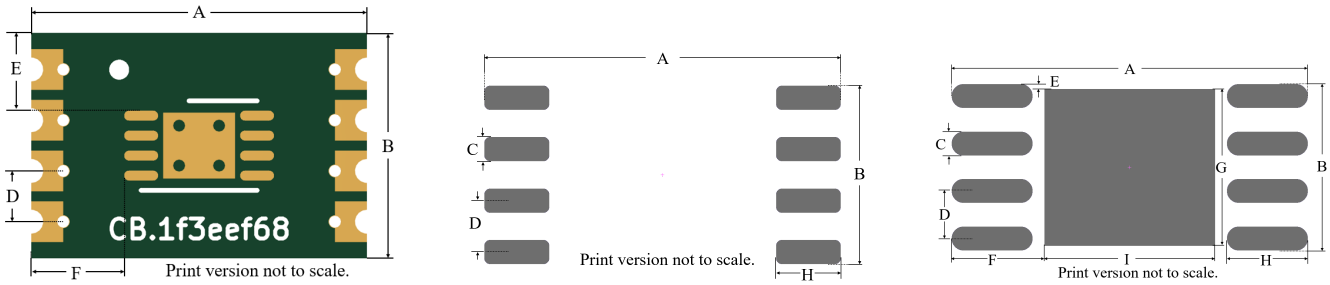
This device is a drop-in footprint to footprint adapter for your existing PBC design. Each Chip-Bridge Technologies adapter is designed to fit on the stated **Host Footprint**, and provide a **Guest Footprint** with electrical connections for your replacement IC.

Visit chipbridgetech.com/products to find our full product catalog. If you have questions or would like to request a design specific to your application, please contact our support team at support@chipbridgetech.com.

Chip-Bridge Technologies Adapaters are a patent pending design.



Mechanical Specifications



(a) Adapter Diagram (b) Host Footprint (c) Guest Footprint

Figure 2: Mechanical Outline

Print version not to scale.

Table 3: Mechanical Specification

	Units	A	B	C	D	E	F	G	H	I
Adapter[1]	mm	5.64 ± 0.127	8.4 ± 0.127	-	1.27	1.96	2.32	-	-	-
Host Footprint[1,2]	mm	8.80	4.41	0.60	1.27	-	-	-	1.60	-
Guest Footprint[1,3]	mm	3.75	1.75	0.25	0.5	-	-	1.65	0.85	0.3

[1] Tolerances ±0.1mm unless otherwise stated.
[2] Host IC Reference Drawing: microchip.com/downloads/en/DeviceDoc/20005045C.pdf#page=23
[3] Guest IC Reference Drawing: microchip.com/downloads/en/DeviceDoc/8L_TDFN_2x3_MN_C04-0129E-MN.pdf

Trace Specifications

Table 4: Adapter Trace Specifications

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Trace Resistance	R_{trace}[4]	0.1	2.7	15.0	mΩ	20°C
Trace to Trace Clearance	$d_{clearance}$		250 ± 13		µm	

[4] Calculated values.

Datasheet Updates

The information in this document is subject to change without notice.